

AMPMODU | AMPMODU Headers

TE Internal #: 280371-3

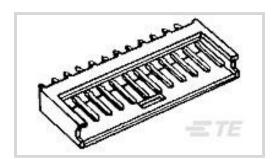
PCB Mount Header, Vertical, Board-to-Board, 4 Position, 2.54 mm [. 1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder,

AMPMODU Headers

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 4

Number of Rows: 1

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	4
Number of Rows	1

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	750 V	
---------------------------------------	-------	--

Body Features

Connector Profile	Standard
Primary Product Color	Black

Contact Features

PCB Contact Termination Area Plating Material Thickness	2.5 µm
Contact Shape & Form	Round



Termination Post & Tail Length Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention Muth Mating Alignment Muting Alignment Muting Alignment Type PCB Mount Retention PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material Dimensions Row-to-Row Spacing Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Power & Signal		
Contact Base Material Gold Contact Mating Area Plating Material Gold Contact Mating Area Plating Material Thickness .762 µm[30 µin] Contact Type Pin Termination Features Termination Post & Tail Length .3.5 mm[, 138 in] Termination Method to Printed Circuit Board .7 mm[, 138 in] Termination Method to Printed Circuit Board .7 mm[, 138 in] Mating Retention .7 with .7 mm[, 138 in] Mating Retention .7 with .7 mm[, 138 in] Mating Alignment .7 with .7 mm[, 138 in] Mating Alignment .7 without .7 mm[, 138 in] Mating Alignment Type .7 mm[, 138 in] Mating Alignment .7 without .7 mm[, 138 in] Mating Alignment .7 mm[, 138 in] Mati	Contact Mating Area Plating Material Finish	Bright
Contact Mating Area Plating Material Contact Type Pin Contact Type Pin Termination Features Lermination Post & Tail Length Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention Panel Mount Feature Without Mating Alignment Mating Alignment Type PCB Mount Alignment Without Connector Mounting Type Board Mount Connector Mounting Type Board Mount Connector Mounting Type Conterline (Pitch) Housing Material Dimensions Row to Row Spacing Standard Operating Temperature Rating Operation/Application Circuit Application Circuit Application Packaging Countity Packaging Countity Packaging Countity Packaging Countity Pin Packaging Countity Pin	PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness 7.62 µm[30 µin] Contact Type Pin Termination Features Termination Post & Tail Length 3.5 mm[.138 in] Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Retention With Panel Mount Feature Without Mating Alignment Type Polarization PCB Mount Alignment Without Connector Mounting Type Board Mount Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Themperature Rating Standard Operating Temperature Rating Standard Operating Temperature Range Peakaging Quantity 1000	Contact Base Material	Brass
Termination Features Termination Post & Tail Length 3.5 mm[.138 in] Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Retention With Panel Mount Feature Without Mating Alignment With Mating Alignment Without Mating Alignment Without PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range -45 – 105 °CT-85 – 221 °F] Operation/Application Circuit Application Power & Signal Packaging Features Packaging Ouentity 1000	Contact Mating Area Plating Material	Gold
Termination Features Termination Post & Tail Length 3.5 mm[.138 in] Termination Method to Printed Circuit Board Through Hole Solder Mechanical Attachment Mating Retention With Panel Mount Feature Without Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range 65 105 °C 85 221 °F Operation/Application Packaging Features Packaging Guantity 1000	Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Termination Post & Tail Length Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention Mating Retention Mating Alignment Mating Alignment Mating Alignment Type POB Mount Retention PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material Dimensions Row-to-Row Spacing Doerating Temperature Rating Operating Temperature Range Operation/Application Circuit Application Packaging Features Packaging Guantity 1 Through Hole - Solder With Device Hole - Solder With Device Hole - Solder Without Without Without Connector Mounting Type Board Mount Without 2.54 mm[.1 in] Thermoplastic Dimensions Standard Operating Temperature Rating Operating Temperature Range Operation Application Power & Signal Packaging Guantity 1000	Contact Type	Pin
Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention With Panel Mount Feature Without Mating Alignment Mating Alignment Type Polarization Without Mating Alignment Type Polarization Without Mount Retention Without Connector Mounting Type Board Mount Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operat	Termination Features	
Mechanical Attachment Mating Retention With Panel Mount Feature Without Mating Alignment Mating Alignment Type Polarization PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range 65 – 105 °C[85 – 221 °F] Operation/Application Circuit Application Power & Signal Packaging Features Packaging Quantity 1000	Termination Post & Tail Length	3.5 mm[.138 in]
Mating Retention With Panel Mount Feature Without Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2,54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2,54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range -45 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	Termination Method to Printed Circuit Board	Through Hole - Solder
Panel Mount Feature Mating Alignment Mating Alignment Type POB Mount Retention PCB Mount Alignment PCB Mount Alignment PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Contectine (Pitch) Ausing Material Dimensions Row-to-Row Spacing Standard Operating Temperature Rating Operation/Application Circuit Application Packaging Quantity Packaging Quantity Polarization Without Without Without Without Without Without Author W	Mechanical Attachment	
Mating Alignment Type Polarization PCB Mount Retention Without PCB Mount Alignment Type Board Mount PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	Mating Retention	With
Mating Alignment Type Polarization Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Power & Signal Packaging Peatures Packaging Guantity 1000	Panel Mount Feature	Without
PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range 65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Packaging Features Packaging Guantity 1000	Mating Alignment	With
PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	Mating Alignment Type	Polarization
Connector Mounting Type Housing Features Centerline (Pitch) Housing Material Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Packaging Features Packaging Quantity Board Mount 2.54 mm[.1 in] Thermoplastic Thermoplastic Standard -65 - 105 °C[-85 - 221 °F] Power & Signal	PCB Mount Retention	Without
Housing Features Centerline (Pitch) Augusting Material Centerline (Pitch) Housing Material Thermoplastic Thermoplastic Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	PCB Mount Alignment	Without
Centerline (Pitch) Housing Material Commensions Row-to-Row Spacing Usage Conditions Housing Temperature Rating Operating Temperature Range Circuit Application Packaging Features Packaging Quantity 2.54 mm[.1 in] Thermoplastic 2.54 mm[.1 in] Standard -65 – 105 °C[-85 – 221 °F] Power & Signal	Connector Mounting Type	Board Mount
Housing Material Pimensions Row-to-Row Spacing Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Packaging Features Packaging Quantity Thermoplastic 2.54 mm[.1 in] Standard -65 – 105 °C[-85 – 221 °F] Power & Signal	Housing Features	
Dimensions Row-to-Row Spacing 2.54 mm[.1 in] Usage Conditions Housing Temperature Rating Standard Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Power & Signal Packaging Features Packaging Quantity 1000	Centerline (Pitch)	2.54 mm[.1 in]
Row-to-Row Spacing Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Circuit Application Packaging Features Packaging Quantity 2.54 mm[.1 in] Standard -65 – 105 °C[-85 – 221 °F] Power & Signal	Housing Material	Thermoplastic
Usage Conditions Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	Dimensions	
Housing Temperature Rating Operating Temperature Range -65 – 105 °C[-85 – 221 °F] Operation/Application Circuit Application Power & Signal Packaging Features Packaging Quantity 1000	Row-to-Row Spacing	2.54 mm[.1 in]
Operating Temperature Range Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	Usage Conditions	
Operation/Application Circuit Application Packaging Features Packaging Quantity 1000	Housing Temperature Rating	Standard
Circuit Application Power & Signal Packaging Features Packaging Quantity 1000	Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Packaging Features Packaging Quantity 1000	Operation/Application	
Packaging Quantity 1000	Circuit Application	Power & Signal
	Packaging Features	
Packaging Type Box	Packaging Quantity	1000
	Packaging Type	Box

Product Compliance



For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

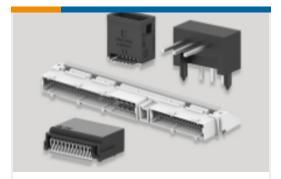


Also in the Series | AMPMODU Headers











Connector Caps & Covers(1)

PCB Connector Mounting(1)

PCB Headers & Receptacles(4871)

PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Connector Contacts(65)

Customers Also Bought



IM06DGR=IM RELAY 140mW 12V



SR6D4024



3522 4R7 5% 3W





TE Part #CH02054001 VERSAFLEX-3/4-0-SP



TE Part #280378-2 4P MODU II SHRD HDR, RT ANG, 0.38





Documents

Product Drawings

4P AMPMODU II SHRD HDR, ST, 0.76AU

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_280371-3_U_c-280371-3-u.2d_dxf.zip



English

Customer View Model

ENG_CVM_CVM_280371-3_U_c-280371-3-u.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_280371-3_U_c-280371-3-u.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Environmental Compliance

MD_280371-3_09032011152

English

MD_280371-3_09032011152

English